



Material Content Data Sheet



Sales Product Name	TLE84110EL			Issued		28. August 2013		
MA#	MA000982448							
Package	PG-SSOP-24-4			Weight*		151.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.466	3.62	3.62	36162	36162
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		445	
	non noble metal	iron	7439-89-6	1.345	0.89		8898	
	non noble metal	copper	7440-50-8	54.617	36.13	37.07	361310	370764
wire	noble metal	gold	7440-57-5	0.567	0.38	0.38	3753	3753
encapsulation	organic material	carbon black	1333-86-4	0.169	0.11		1118	
	plastics	epoxy resin	-	7.775	5.14		51431	
	inorganic material	silicondioxide	60676-86-0	76.562	50.64	55.89	506484	559033
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19257	19257
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1550	1550
glue	plastics	epoxy resin	-	0.358	0.24		2370	
	noble metal	silver	7440-22-4	1.075	0.71	0.95	7111	9481
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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